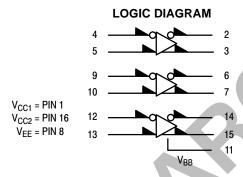
High Speed Triple Line Receiver

The MC10216 is a high speed triple differential amplifier designed for use in sensing differential signals over long lines. The base bias supply (V_{BB}) is made available at pin 11 to make the device useful as a Schmitt trigger, or in other applications where a stable reference voltage is necessary.

Active current sources provide the MC10216 with excellent common mode noise rejection. If any amplifier in a package is not used, one input of that amplifier must be connected to V_{BB} (pin 11) to prevent upsetting the current source bias network.

Complementary outputs are provided to allow driving twisted pair lines, to enable cascading of several amplifiers in a chain, or simply to provide complement outputs of the input logic function.

- $P_D = 100 \text{ mW typ/pkg (No Load)}$
- $t_{pd} = 1.8$ ns typ (Single ended)
- = 1.5 ns typ (Differential)
- t_r , $t_f = 1.5$ ns typ (20%–80%)



 $^*V_{BB}$ to be used to supply bias to the MC10216 only and bypassed (when used) with 0.01 μ F to 0.1 μ F capacitor.

When the input pin with bubble goes positive, it's respective output pin with bubble goes positive.

DIP PIN ASSIGNMENT



Pin assignment is for Dual–in–Line Package.
For PLCC pin assignment, see the Pin Conversion Tables on page 18 of the ON Semiconductor MECL Data Book (DL122/D).



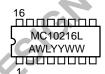
ON Semiconductor

http://onsemi.com

MARKING DIAGRAMS



CDIP-16 L SUFFIX CASE 620





PDIP-16 P SUFFIX CASE 648





PLCC-20 FN SUFFIX CASE 775



A = Assembly Location

WL = Wafer Lot YY = Year

WW = Work Week

ORDERING INFORMATION

Device	Package	Shipping
MC10216L	CDIP-16	25 Units / Rail
MC10216P	PDIP-16	25 Units / Rail
MC10216FN	PLCC-20	46 Units / Rail

ELECTRICAL CHARACTERISTICS

				200	I	Test Limits	•		F0.0	
		Pin Under		0°C		+25°C	l		5°C 	ļ
Characteristic	Symbol	Test	Min	Max	Min	Тур	Max	Min	Max	Un
Power Supply Drain Current	Ι _Ε	8		27		20	25		27	mA
Input Current	I _{inH}	4		180			115		115	μΑσ
	I _{CBO}	4 9		1.5 1.5			1.0 1.0		1.0 1.0	μΑσ
Output Voltage Logic 1	V _{OH}	2 3	-1.060 -1.060	-0.890 -0.890	-0.960 -0.960		-0.810 -0.810	-0.890 -0.890	-0.700 -0.700	Vd
Output Voltage Logic 0	V _{OL}	2 3	-1.890 -1.890	-1.675 -1.675	-1.850 -1.850		-1.650 -1.650	-1.825 -1.825	-1.615 -1.615	Vd
Threshold Voltage Logic 1	V _{OHA}	2 3	-1.080 -1.080		-0.980 -0.980			-0.910 -0.910		Vd
Threshold Voltage Logic 0	V_{OLA}	2 3		-1.655 -1.655			-1.630 -1.630		-1.595 -1.595	Vd
Reference Voltage	V_{BB}	11	-1.420	-1.280	-1.350	_	-1.230	-1.295	- 1.150	Vd
Switching Times (50Ω Load)						1				ns
Propagation Delay	t ₄₊₂₊ t ₄₋₂₋ t ₄₊₃₋ t ₄₋₃₊	2 2 3 3	1.0 1.0 1.0 1.0	2.6 2.6 2.6 2.6	1.0 1.0 1.0 1.0	1.8* 1.8* 1.8* 1.8*	2.5 2.5 2.5 2.5 2.5	1.0 1.0 1.0 1.0	2.8 2.8 2.8 2.8	
	4-3+									
Rise Time (20 to 80%)	t ₂₊ t ₃₊	2 3	1.0 1.0	2.6 2.6	1.0 1.0	1.5 1.5	2.5 2.5	1.0 1.0	2.8 2.8	
Rise Time (20 to 80%) Fall Time (20 to 80%) Delay is 1.5ns when inputs are Delay is 1.8ns when inputs are	t ₂₊ t ₃₊ t ₂₋	3 2 3 erentially.	1.0	2.6 2.6	1.0 1.0	1.5 1.5				

ELECTRICAL CHARACTERISTICS (continued)

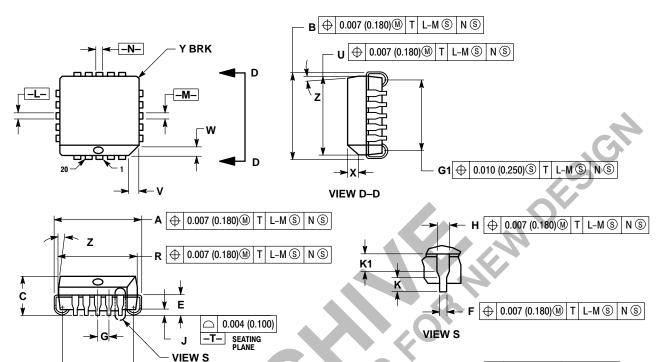
				TEST VOLTAGE VALUES (Volts)						
	(@ Test Tem	perature	V _{IHmax}	V _{ILmin}	V _{IHAmin}	V _{ILAmax}	V _{BB}	V _{EE}	
			-30°C	-0.890	-1.890	-1.205	-1.500	From	-5.2	
			+25°C	-0.810	-1.850	-1.105	-1.475	Pin	-5.2	
			+85°C	-0.700	-1.825	-1.035	-1.440	11	- 5.2	
			Pin	TES	T VOLTA	SE APPLIED	TO PINS L	ISTED BEL	.ow	α, ,
Characteri	stic	Symbol	Under Test	V _{IHmax}	V _{ILmin}	V _{IHAmin}	V _{ILAmax}	V _{BB}	V _{EE}	(V _{CC}) Gnd
Power Supply Drain C	Current	ΙE	8	4, 9, 12				5, 10, 13	8	1, 16
Input Current		I _{inH}	4	4	9, 12			5, 10, 13	8	1, 16
		Ісво	4 9		9, 12 4, 12			5, 10, 13 5, 10, 13	8, 4 8, 9	1, 16
Output Voltage	Logic 1	V _{OH}	2 3	4 9, 12	9, 12 4			5, 10, 13 5, 10, 13	8 8	1, 16 1, 16
Output Voltage	Logic 0	V _{OL}	2 3	9, 12 4	4 9, 12			5, 10, 13 5, 10, 13	8 8	1, 16 1, 16
Threshold Voltage	Logic 1	V _{OHA}	2 3	9, 12	9, 12	4	4	5, 10, 13 5, 10, 13	8 8	1, 16 1, 16
Threshold Voltage	Logic 0	V _{OLA}	2 3	9, 12	9, 12	4	4	5, 10, 13 5, 10, 13	8 8	1, 16 1, 16
Reference Voltage		V_{BB}	11		\ \ \			5, 10, 13	8	1, 16
Switching Times	(50Ω Load)					Pulse In	Pulse Out		-3.2 V	+2.0 V
Propagation Delay		t ₄₊₂₊ t ₄₋₂₋ t ₄₊₃₋ t ₄₋₃₊	2 2 3 3			4 4 4 4	2 2 3 3	5, 10, 13 5, 10, 13 5, 10, 13 5, 10, 13	8 8 8	1, 16 1, 16 1, 16 1, 16
Rise Time	(20 to 80%)	t ₂₊ t ₃₊	2 3			4 4	2 3	5, 10, 13 5, 10, 13	8 8	1, 16 1, 16
Fall Time	(20 to 80%)	t ₂₋ t ₃₋	2 3			4 4	2 3	5, 10, 13 5, 10, 13	8 8	1, 16 1, 16

Each MECL 10,000 series circuit has been designed to meet the dc specifications shown in the test table, after thermal equilibrium has been established. The circuit is in a test socket or mounted on a printed circuit board and transverse air flow greater than 500 linear fpm is maintained. Outputs are terminated through a 50-ohm resistor to -2.0 volts. Test procedures are shown for only one gate. The other gates are tested in the same manner.

PACKAGE DIMENSIONS

PLCC-20 **FN SUFFIX**

PLASTIC PLCC PACKAGE CASE 775-02 ISSUE C



NOTES:

- OTES:

 1. DATUMS -L-, -M-, AND -N- DETERMINED WHERE TOP OF LEAD SHOULDER EXITS PLASTIC BODY AT MOLD PARTING LINE.

 2. DIMENSION G1, TRUE POSITION TO BE MEASURED AT DATUM -T-, SEATING PLANE.

 3. DIMENSIONS R AND U DO NOT INCLUDE MOLD FLASH. ALLOWABLE MOLD FLASH IS 0.010 (0.250) PER SIDE.

 4. DIMENSIONING AND TOLERANCING PER ANSI V14 5M 1982
- Y14.5M, 1982. CONTROLLING DIMENSION: INCH.
- THE PACKAGE TOP MAY BE SMALLER THAN THE PACKAGE BOTTOM BY UP TO 0.012 (0.300). DIMENSIONS R AND U ARE DETERMINED AT THE OUTERMOST EXTREMES OF THE PLASTIC BODY

EXCLUSIVE OF MOLD FLASH, TIE BAR BURRS, GATE BURRS AND INTERLEAD FLASH, BUT INCLUDING ANY MISMATCH BETWEEN THE TOP AND BOTTOM OF THE PLASTIC BODY.

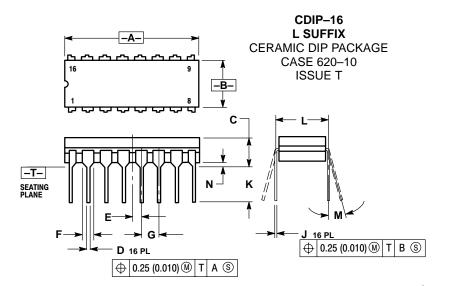
DIMENSION H DOES NOT INCLUDE DAMBAR PROTRUSION OR INTRUSION. THE DAMBAR PROTRUSION(S) SHALL NOT CAUSE THE H DIMENSION TO BE GREATER THAN 0.037 (0.940). THE DAMBAR INTRUSION(S) SHALL NOT CAUSE THE H DIMENSION TO BE SMALLER THAN 0.025 (0.635).

	INC	HES	MILLIM	ETERS
DIM	MIN	MAX	MIN	MAX
Α	0.385	0.395	9.78	10.03
В	0.385	0.395	9.78	10.03
С	0.165	0.180	4.20	4.57
Ε	0.090	0.110	2.29	2.79
F	0.013	0.019	0.33	0.48
G	0.050	BSC	1.27	BSC
Н	0.026	0.032	0.66	0.81
J	0.020		0.51	
K	0.025		0.64	
R	0.350	0.356	8.89	9.04
U	0.350	0.356	8.89	9.04
٧	0.042	0.048	1.07	1.21
W	0.042	0.048	1.07	1.21
X	0.042	0.056	1.07	1.42
Υ		0.020		0.50
Z	2°	10°	2°	10 °
G1	0.310	0.330	7.88	8.38
K1	0.040		1.02	

G1 ⊕ 0.010 (0.250)③ T L-M ⑤ N ⑤

OENICE NOT RECO

PACKAGE DIMENSIONS



NOTES:

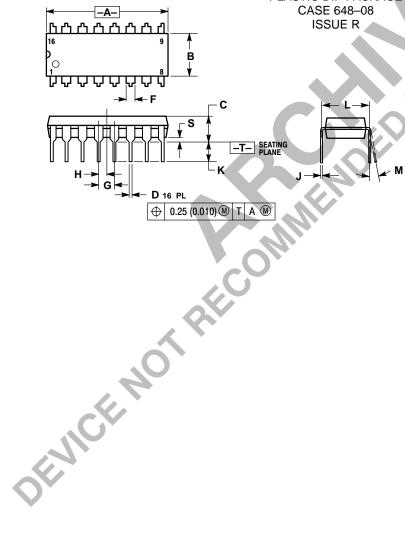
- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 CONTROLLING DIMENSION: INCH.
 DIMENSION LTO CENTER OF LEAD WHEN CONTROLLING DIMENSION LTO CENTER OF LEAD WHEN

- FORMED PARALLEL

 DIMENSION F MAY NARROW TO 0.76 (0.030)
 WHERE THE LEAD ENTERS THE CERAMIC
 BODY.

	INC	HES	MILLIN	IETERS	
DIM	MIN	MAX	MIN	MAX	
Α	0.750	0.785	19.05	19.93	
В	0.240	0.295	6.10	7.49	
C		0.200		5.08	
D	0.015	0.020	0.39	0.50	
E	0.050	BSC	1.27 BSC		
F	0.055	0.065	1.40	1.65	
G	0.100	BSC	2.54	BSC	
Н	0.008	0.015	0.21	0.38	
K	0.125	0.170	3.18	4.31	
L	0.300	BSC	7.62		
M	0 °	15°	0 °	15°	
N	0.020	0.040	0.51	1.01	





- NOTES:
 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: INCH.
 3. DIMENSION L TO CENTER OF LEADS WHEN FORMED PARALLEL.
 4. DIMENSION B DOES NOT INCLUDE MOLD FLASH.
 5. ROUNDED CORNERS OPTIONAL

	INC	HES	MILLIN	IETERS	
DIM	MIN MAX		MIN	MAX	
Α	0.740	0.770	18.80	19.55	
В	0.250	0.270	6.35	6.85	
С	0.145	0.175	3.69	4.44	
D	0.015	0.021	0.39	0.53	
F	0.040	0.70	1.02	1.77	
G	0.100	BSC	2.54 BSC		
Н	0.050	BSC	1.27	BSC	
J	0.008	0.015	0.21	0.38	
K	0.110	0.130	2.80	3.30	
L	0.295	0.305	7.50	7.74	
M	0°	10°	0°	10 °	
S	0.020	0.040	0.51	1.01	

Notes



Notes





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